

10/059404  
01/31/02

PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10059404	FILING DATE 01/31/2002	CLASS 439	SUBCLASS	GAU 2833	EXAMINER <i>[Signature]</i>
<b>**APPLICANTS:</b> Fulk Mikel; Key Jason; Bednarz Jack; Lawlyes Daniel;					
<b>**CONTINUING DATA VERIFIED:</b> <i>None</i>					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> <i>None</i>					
PG-PUB		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed		<input type="checkbox"/> yes <input checked="" type="checkbox"/> no		ATTORNEY DOCKET NO	
35 USC 119 conditions met		<input type="checkbox"/> yes <input checked="" type="checkbox"/> no		DP-305004	
Verified and Acknowledged Examiners's initials		<i>[Signature]</i>			
TITLE : High density wire bondable connector assembly					
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)					

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Total Claims	
		Print Claim for O.G	
<b>ISSUE FEE</b>		<b>DRAWING</b>	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
		Primary Examiner	
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		Applicati n Examiner	
		<b>PREPARED FOR ISSUE</b>	
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